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(54) Title: COMPOSITIONS FOR REMOVING PHOTORESIST AND ETCH RESIDUES, METHODS OF USING AND USE
THEREOF

(57) Abstract: A method and cleaning composition for microelectronic devices or semiconductor substrates that includes (i) at least one organic solvent; (ii) at least one amine that is free of carboxylic acid moieties; (iii) water; and (iv) a corrosion inhibitor including one or more of (a) an amino acid, (b) an azole, and (c) a phenolic acid, where the remover solution is free of dimethylsulfoxide, N-methylpyrrolidone and dimethylacetamide.

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